

HEX Size	Part Number	V <sub>DS</sub>	R <sub>DS(on)</sub>	Die Outline Figure	Recommended Source Bonding Wire mils mm	Equivalent Device Type
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**HEXFET® Die**

3	IRFC9230	-200	0.8	D41	8	0.2	IRF9630
3	IRFC9130	-100	0.3	D40	10	0.25	IRF9530
2	IRFC9220*	-200	1.5	D38	8	0.2	IRF9620
2	IRFC9120	-100	0.6	D37	8	0.2	IRF9520
1	IRFC9210*	-200	3	D35	5	0.13	IRF9610
1	IRFC9014	-60	0.5	D33	5	0.13	IRFR9014
2	IRFC9024	-60	0.28	D36	10	0.25	IRF9Z24

**Logic Level**

**N-Channel**

4	IRLC140	100	0.077	D20	15	0.38	IRL540
1	IRLC014	60	0.2	D2	5	0.13	IRLZ14
1	IRLC110	100	0.54	D3	5	0.13	IRL510
2	IRLC024	60	0.1	D6	10	0.25	IRLZ24
2	IRLC120	100	0.27	D7	8	0.2	IRL520
3	IRLC034	60	0.05	D12	15	0.38	IRLZ34
3	IRLC130	100	0.16	D13	10	0.25	IRL530
4	IRLC044	60	0.028	D18	20	0.51	IRLZ44

Common Characteristics:  $I_{DSS}$  @  $V_{DS}$  250 $\mu$ A

500nA

$V_{GS(th)}$  Standard gate: min 2V, max 4V with  $V_{DS}=V_{GS}$ ,  $I_D=250\mu$ A

$V_{GS(th)}$  Logic level: min 1V, max 2V with  $V_{DS}=V_{GS}$ ,  $I_D=250\mu$ A

$R_{DS(on)}$  Standard gate: measured @  $V_{GS}=10V$

Logic level: measured @  $V_{GS}=5V$

